LM4985 Boomer™ Audio Power Amplifier Series Stereo 135mW Low Noise Headphone Amplifier with Selectable Capacitively Coupled or Output Capacitor-less (OCL) Output and Digitally Controlled (I^2C) Volume Control

Check for Samples: LM4985, LM4985TMEVAL

FEATURES

- **OCL or Capacitively Coupled Outputs (Patent Pending)**
- **I^2C Digitally Controlled Volume Control**
- **Available in Space-Saving 0.4mm Lead-Pitch DSBGA Package**
- **Volume Control Range: –76dB to +18dB**
- **Ultra Low Current Shutdown Mode**
- **2.3V - 5.5V Operation**
- **Ultra Low Noise**

APPLICATIONS

- **Mobile Phones**
- **PDAs**
- **Portable Electronics Devices**
- **MP3 Players**

KEY SPECIFICATIONS (V_{DD} = 3.6V)

- **PSRR: 217Hz and 1kHzs**
  - **Output Capacitor-Less (OCL)**
    - **f_{RIPPLE} = 217Hz, 77dB (Typ)**
    - **f_{RIPPLE} = 1kHz, 76dB (Typ)**
  - **Capacitor Coupled (C-CUPL)**
    - **f_{RIPPLE} = 217Hz, 63dB (Typ)**
    - **f_{RIPPLE} = 1kHz, 62dB (Typ)**
- **Output Power Per Channel (f_{IN} = 1kHz, THD+N = 1%), R_L = 16Ω, OCL**
  - **V_{DD} = 2.5V, 31mW (Typ)**
  - **V_{DD} = 3.6V, 68mW (Typ)**
  - **V_{DD} = 5.0V, 135mW (Typ)**
- **THD+N (f = 1kHz)**
  - **R_{LOAD} = 16Ω, OCL, P_{OUT} = 60mW, 0.60**
  - **R_{LOAD} = 32Ω, OCL, P_{OUT} = 33mW, 0.031**
- **Shutdown Current, 0.1µA (Typ)**

DESCRIPTION

The LM4985 is a stereo audio power amplifier with internal digitally controlled volume control. This amplifier is capable of delivering 68mW_{RMS} per channel into a 16Ω load or 38mW_{RMS} per channel into a 32Ω load at 1% THD when powered by a 3.6V power supply and operating in the OCL mode.

Boomer audio power amplifiers were designed specifically to provide high quality output power with a minimal amount of external components. To that end, the LM4985 features two functions that optimize system cost and minimize PCB area: an integrated, digitally controlled (I^2C bus) volume control and an operational mode that eliminates output signal coupling capacitors (OCL mode). Since the LM4985 does not require bootstrap capacitors, snubber networks, or output coupling capacitors, it is optimally suited for low-power, battery powered portable systems. For added design flexibility, the LM4985 can also be configured for single-ended capacitively coupled outputs.

The LM4985 features a current shutdown mode for micropower dissipation and thermal shutdown protection.

Block Diagram

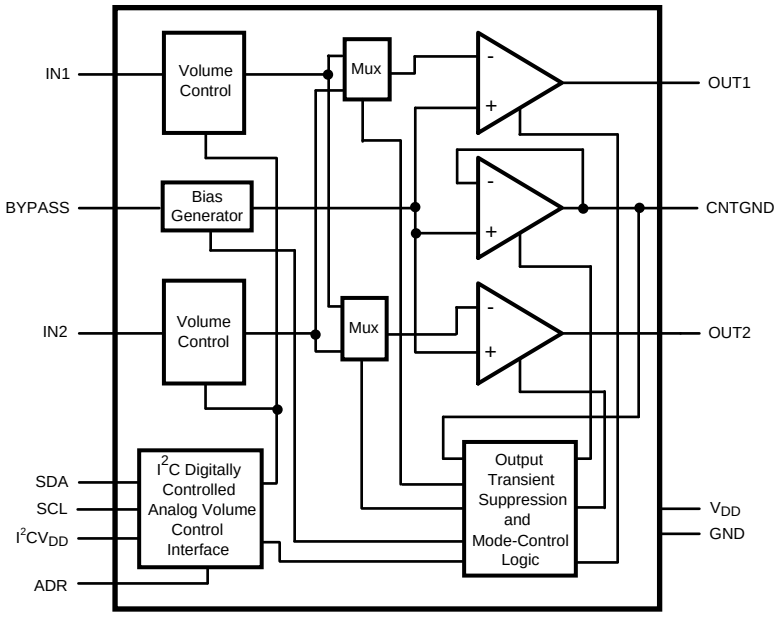


Figure 1. Block Diagram

Typical Application

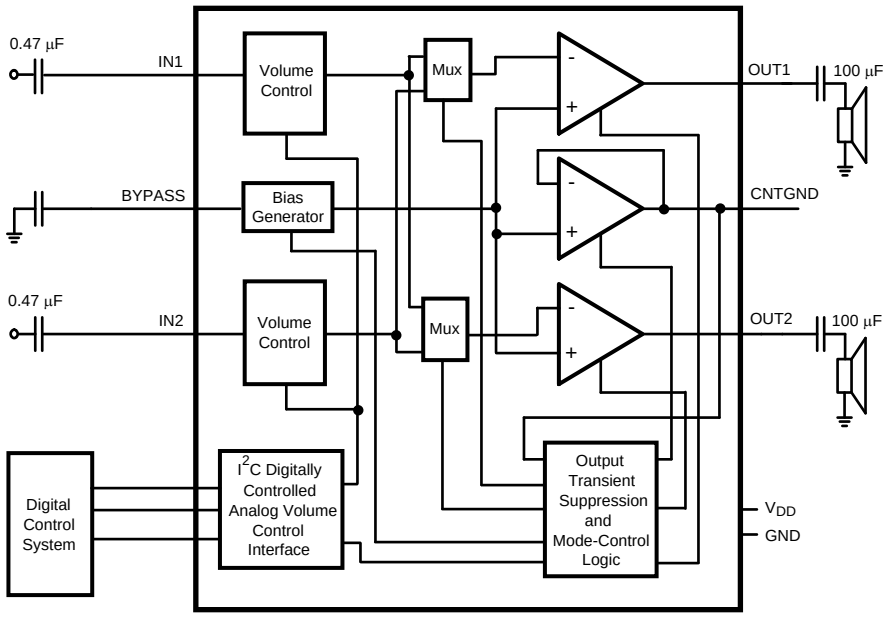


Figure 2. Typical Capacitively Coupled Output Configuration Circuit

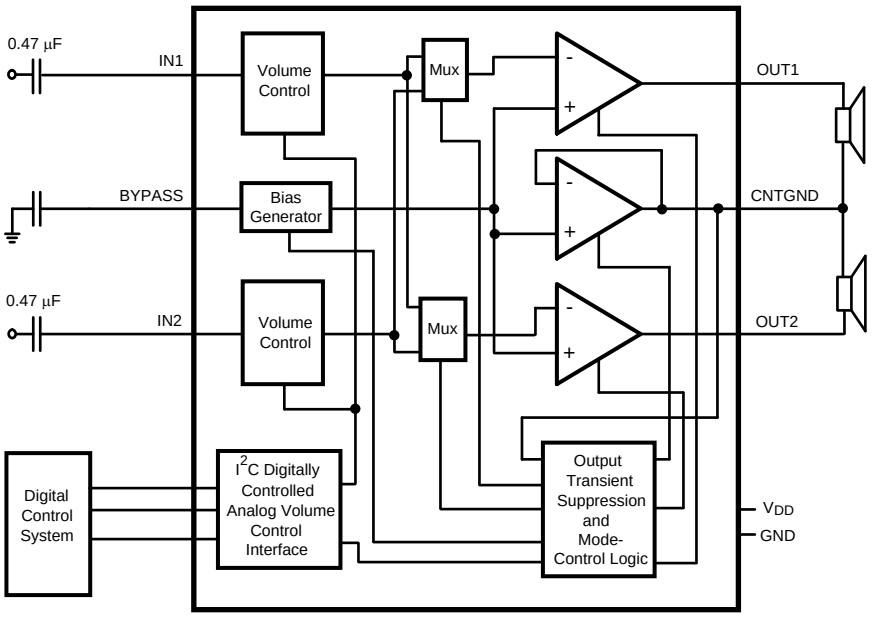


Figure 3. Typical OCL Output Configuration Circuit

Connection Diagram

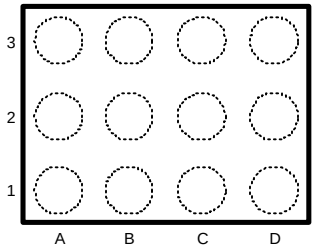


Figure 4. DSBGA Package
Top View
See NS Package Number YFQ0012

PIN REFERENCE, NAME, AND FUNCTION

Reference	Name	Function
A1	ADR	I^2C serial interface address input.
A2	IN2	Analog signal input two.
A3	OUT2	Power amplifier two output.
B1	SDA	I^2C serial interface data input.
B2	BYPASS	The internal $V_{DD}/2$ ac bypass node.
B3	CNTGND	In OCL mode, this is the ac ground return. It is biased to $V_{DD}/2$. Leave unconnected for C-CUPL mode.
C1	SCL	I2C serial interface clock input.
C2	GND	The LM4985's power supply ground input.
C3	V_{DD}	The LM4985's power supply voltage input.
D1	I^2CV_{DD}	I^2C serial interface power supply input. Can be connected to the same supply that is connected to the V_{DD} pin.
D2	IN1	Analog signal input one.
D3	OUT1	Power amplifier one output.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)(2)

Supply Voltage (V_{DD}, I^2CV_{DD})		6.0V
Storage Temperature		−65°C to +150°C
Input Voltage (IN1, IN2, OUT1, OUT2, BYPASS, CNTGND, GND pins relative to the V_{DD} pin)		-0.3V to V_{DD} + 0.3V
Input Voltage (ADR, SDA, SCL pins, relative to the I^2CV_{DD} pin)		-0.3V to I^2CV_{DD} + 0.3V
Power Dissipation(3)		Internally Limited
ESD Susceptibility(4)		2000V
ESD Susceptibility(5)		200V
Junction Temperature		150°C
Thermal Resistance	θ_{JA}	109°C/W

(1) All voltages are measured with respect to the GND pin unless otherwise specified.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
(3) The maximum power dissipation must be derated at elevated temperatures and is dictated by TJ_{MAX}, θ_{JA}, and the ambient temperature, T_A. The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A)/ \theta_{JA}$ or the number given in Absolute Maximum Ratings, whichever is lower. For the LM4985, see power derating currents for more information.
(4) Human Body Model: 100pF discharged through a 1.5kΩ resistor.
(5) Machine Model: 200pF ≤ C_{mm} ≤ 220pF discharged through all pins.

Operating Ratings

Temperature Range	$T_{MIN} \le T_A \le T_{MAX}$	−40°C ≤ T_A ≤ 85°C
Supply Voltage	V_{DD}	2.3V ≤ V_{CC} ≤ 5.5V
	I^2CV_{DD}	1.7V ≤ I^2CV_{DD} ≤ 5.5V

Electrical Characteristics V_{DD} = 5V(1)(2)

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ(3)	Limit(4)(5)	
I_{DD}	Quiescent Power Supply Current	V_{IN} = 0V, I_{OUT} = 0A Single-Channel no load OCL Single-Channel no load C-CUPL Dual-Channel no load OCL Dual-Channel no load C-CUPL	 2 1.5 3 2.3	 4.9 3.8	mA (max)
I_{SD}	Shutdown Current	$V_{SHUTDOWN}$ = GND	0.1	1.0	µA (max)
V_{SDIH}	Logic Voltage Input High			3.5	V (min)
V_{SDIL}	Logic Voltage Input Low			1.5	V (max)

(1) All voltages are measured with respect to the GND pin unless otherwise specified.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
(3) Typicals are measured at 25°C and represent the parametric norm.
(4) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).
(5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.

Electrical Characteristics V_{DD} = 5V[1][2] (continued)

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ[3]	Limit[4][5]	
P_O	Output Power	THD ≤ 1%; f_{IN} = 1kHz			
		R_{LOAD} = 16Ω OCL	135	115	
		R_{LOAD} = 16Ω C-CUPL	135		mW (min)
		R_{LOAD} = 32Ω OCL	79	70	
		R_{LOAD} = 32Ω C-CUPL	80		
THD+N	Total Harmonic Distortion + Noise	R_{LOAD} = 16Ω OCL, P_O = 100mW R_{LOAD} = 16Ω C-CUPL, P_O = 100mW R_{LOAD} = 32Ω OCL, P_O = 60mW R_{LOAD} = 32Ω C-CUPL, P_O = 70mW	0.08 0.02 0.04 0.01		%
V_{ON}	Output Noise Voltage	V_{IN} = AC GND, A_V = 0dB, A-weighted	15		µV
PSRR	Power Supply Rejection Ratio	V_{RIPPLE} = 200mVp-p[6] f_{IN} = 217Hz sinewave OCL C-CUPL	 77 65	57	dB (min)
		f_{IN} = 1kHz sinewave OCL C-CUPL	 77 65	60	
Xtalk	Channel-to-channel Crosstalk	P_{out} = 40mW. OCL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 51 56		dB
		P_{out} = 50mW. C-CUPL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 58 68		dB
T_{WU}	Wake Up Time form Shutdown	C_{BYPASS}= 4.7µF[7]			
		WT1 = 0, WT0 = 0 OCL C-CUPL	 75 285		msec
		WT1 = 0, WT0 = 1 OCL C-CUPL	 110 530		
		WT1 = 1, WT0 = 0 OCL C-CUPL	 180 1030		
		WT1 = 1, WT0 = 1 OCL C-CUPL	 320 2050		
R_{IN}	Input Resistance	Stereo mode Mono mode	20 10		kΩ
A_{VMIN}	Minimum Gain	Code = 00000	–76		dB (min)
A_{VMAX}	Maximum Gain	Code = 11111	18		dB (min)
ΔA_V	Gain Accuracy per Step	18dB ≥ A_V ≥ –44dB –44dB ≥ A_V > –76dB	±0.5 ±1.0		dB
V_{OS}	Output Offset Voltage	OCL R_{LOAD} = 32Ω V_{IN} = AC GND	2.0	20	mV (max)

(6) 10Ω terminated input.
(7) The wake-up time (T_{WU}) is calculated using the following formula; T_{WU} = [C_{BYPASS} (VDD) / 2 (I_{BYPASS})] + 40ms.

Electrical Characteristics V_{DD} = 3.6V[1][2]

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ[3]	Limit[4][5]	
I_{DD}	Quiescent Power Supply Current	V_{IN} = 0V, I_{OUT} = 0A			
		Single-Channel no load OCL	1.8	3.1	mA (max)
		Single-Channel no load C-CUPL	1.0		
		Dual-Channel no load OCL	2.1	4	
		Dual-Channel no load C-CUPL	2.3	3	
I_{SD}	Shutdown Current	$V_{SHUTDOWN}$ = GND	0.1	1.0	µA (max)
V_{SDIH}	Logic Voltage Input High			2.52	V (min)
V_{SDIL}	Logic Voltage Input Low			1.08	V (max)
P_O	Output Power	THD+N < 1%, f_{IN} = 1kHz			
		R_{LOAD} = 16Ω OCL	68	60	
		R_{LOAD} = 16Ω C-CUPL	70		mW (min)
		R_{LOAD} = 32Ω OCL	38	34	
		R_{LOAD} = 32Ω C-CUPL	41		
THD+N	Total Harmonic Distortion + Noise	R_{LOAD} = 16Ω OCL, P_O = 60mW R_{LOAD} = 16Ω C-CUPL, P_O = 60mW R_{LOAD} = 32Ω OCL, P_O = 33mW R_{LOAD} = 32Ω C-CUPL, P_O = 38mW	0.06 0.03 0.03 0.03		%
V_{ON}	Output Noise Voltage	V_{IN} = AC GND, A_V = 0dB, A-weighted	15		µV
PSRR	Power Supply Rejection Ratio	V_{RIPPLE} = 200mVp-p[6] f_{IN} = 217Hz sinewave OCL C-CUPL	 77 63	55	dB (min)
		f_{IN} = 1kHz sinewave OCL C-CUPL	 76 62	57	
Xtalk	Channel-to-Channel Crosstalk	P_{out} = 40mW. OCL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 51 56		dB
		P_{out} = 50mW. C-CUPL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 58 69		dB

(1) All voltages are measured with respect to the GND pin unless otherwise specified.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
(3) Typicals are measured at 25°C and represent the parametric norm.
(4) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).
(5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.
(6) 10Ω terminated input.

Electrical Characteristics V_{DD} = 3.6V(1)(2) (continued)

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ(3)	Limit(4)(5)	
T_{WU}	Wake Up Time from Shutdown	C_{BYPASS}= 4.7µF(7)			
		WT1 = 0, WT0 = 0 OCL C-CUPL	 66 222	 93	msec
		WT1 = 0, WT0 = 1 OCL C-CUPL	 92 405		
		WT1 = 1, WT0 = 0 OCL C-CUPL	 143 774		
		WT1 = 1, WT0 =1 OCL C-CUPL	 246 1532		
R_{IN}	Input Resistance	Stereo mode Mono mode	20 10		kΩ
A_{VMIN}	Minimum Gain	Code = 00000	–76	–72	dB (max)
A_{VMAX}	Maximum Gain	Code = 11111	18	17	dB (min)
ΔA_V	Gain Accuracy per Step	18dB ≥ A_V ≥–44dB –44dB ≥ A_V > –76dB	± 0.5 ± 1.0	± 1.0 ± 2.0	dB
V_{OS}	Output Offset Voltage	OCL R_{LOAD} = 32Ω V_{IN} = AC GND	2.0	20	mV (max)

(7) The wake-up time (T_{WU}) is calculated using the following formula; T_{WU} = [C_{BYPASS} (VDD) / 2 (I_{BYPASS})] + 40ms.

Electrical Characteristics V_{DD} = 2.5V(1)(2)

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ(3)	Limit(4)(5)	
I_{DD}	Quiescent Power Supply Current	V_{IN} = 0V, I_{OUT} = 0A Single-Channel no load OCL Single-Channel no load C-CUPL Dual-Channel no load OCL Dual-Channel no load C-CUPL	 1.6 1 2.1 1.6		mA
I_{SD}	Shutdown Current	$V_{SHUTDOWN}$ = GND	0.1		µA
V_{SDIH}	Logic Voltage Input High			1.75	V (min)
V_{SDIL}	Logic Voltage Input Low			0.75	V (max)
P_O	Output Power	THD+N < 1%, f_{IN} = 1kHz R_{LOAD} = 16Ω OCL R_{LOAD} = 16Ω C-CUPL R_{LOAD} = 32Ω OCL R_{LOAD} = 32Ω C-CUPL	 31 33 19 19		mW

(1) All voltages are measured with respect to the GND pin unless otherwise specified.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
(3) Typicals are measured at 25°C and represent the parametric norm.
(4) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).
(5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.

Electrical Characteristics V_{DD} = 2.5V[1][2] (continued)

The following specifications apply for R_L = 16Ω, f = 1kHz, and C_B = 4.7µF unless otherwise specified. Limits apply to T_A = 25°C.

Symbol	Parameter	Conditions	LM4985		Units (Limits)
			Typ[3]	Limit[4][5]	
THD+N	Total Harmonic Distortion + Noise	R_{LOAD} = 16Ω OCL, P_O = 26mW R_{LOAD} = 16Ω C-CUPL, P_O = 20mW R_{LOAD} = 32Ω OCL, P_O = 16mW R_{LOAD} = 32Ω C-CUPL, P_O = 15mW	0.07 0.05 0.06 0.04		%
V_{ON}	Output Noise Voltage	V_{IN} = AC GND, A_V = 0dB, A-weighted	10		µV
PSRR	Power Supply Rejection Ratio	V_{RIPPLE} = 200mVp-p[6] f_{IN} = 217Hz sinewave OCL C-CUPL	 75 59		dB
		f_{IN} = 1kHz sinewave OCL C-CUPL	 75 59		
Xtalk	Channel-to-Channel Crosstalk	P_{out} = 20mW, OCL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 50 55		dB
		P_{out} = 20mW. C-CUPL R_{LOAD} = 16Ω R_{LOAD}= 32Ω	 58 67		dB
T_{WU}	Wake Up Time from Shutdown	C_{BYPASS} = 4.7µF[7]			msec
		WT1 = 0, WT0 = 0 OCL C-CUPL	 66 214		
		WT1 = 0, WT0 = 1 OCL C-CUPL	 92 544		
		WT1 = 1, WT0 = 0 OCL C-CUPL	 145 1053		
		WT1 = 1, WT0 = 1 OCL C-CUPL	 250 2098		
R_{IN}	Input Resistance	Stereo mode Mono mode	20 10		kΩ
A_{VMIN}	Minimum Gain	Code = 00000	–76		dB
A_{VMAX}	Maximum Gain	Code = 11111	18		dB
ΔA_V	Gain Accuracy per Step	18dB ≥ A_V ≥ –44dB –44dB ≥ A_V > –76dB	± 0.5 ± 1.0		dB
V_{OS}	Output Offset Voltage	OCL R_{LOAD} = 32Ω V_{IN} = AC GND	2.0		mV

(6) 10Ω terminated input.
(7) The wake-up time (T_{WU}) is calculated using the following formula; T_{WU} = [C_{BYPASS} (VDD) / 2 (I_{BYPASS})] + 40ms.

External Components Description

(See Figure 2)

Components		Functional Description
1.	C_I	Input coupling capacitor which blocks the DC voltage at the amplifier's input terminals. Also creates a high-pass filter with R_i at f_c = 1/(2π$R_i$$C_i$). Refer to the section **Proper Selection of External Components,** for an explanation of how to determine the value of C_i.
2.	C_S	Supply bypass capacitor which provides power supply filtering. Refer to the POWER SUPPLY BYPASSING section for information concerning proper placement and selection of the supply bypass capacitor.

Components		Functional Description
3.	C_B	Bypass pin capacitor which provides half-supply filtering. Refer to the section, POWER SUPPLY BYPASSING, for information concerning proper placement and selection of C_B
6.	C_o	Output coupling capacitor which blocks the DC voltage at the amplifier's output. Forms a high pass filter with R_L at $f_o = 1/(2\pi R_L C_o)$

Typical Performance Characteristics

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

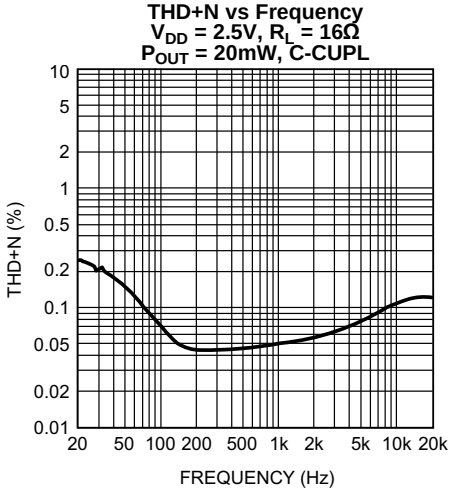


Figure 5.

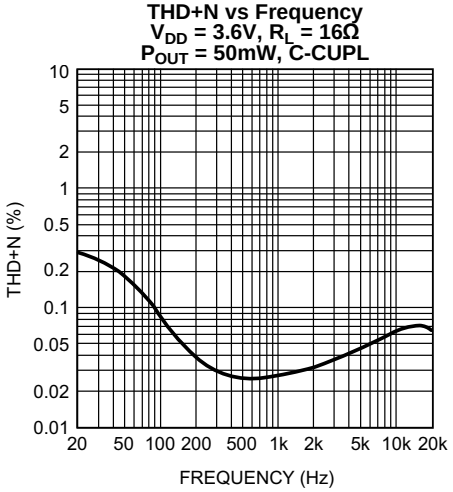


Figure 6.

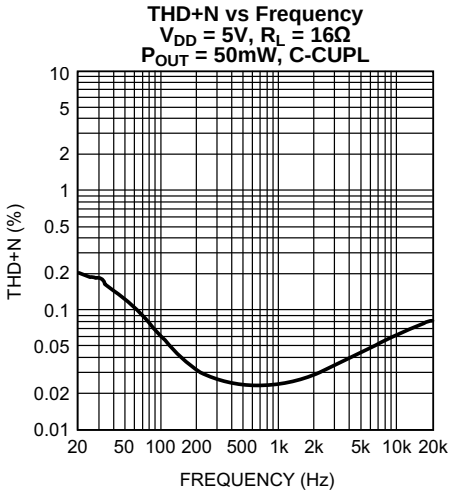


Figure 7.

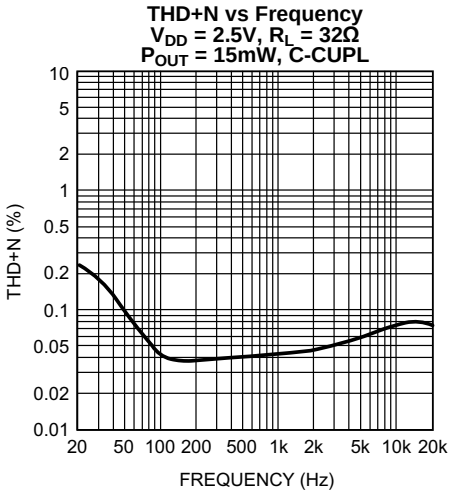


Figure 8.

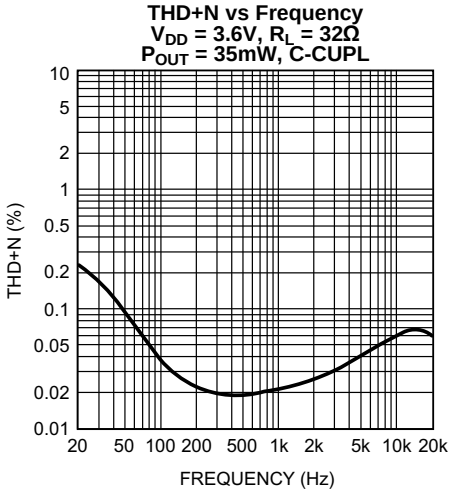


Figure 9.

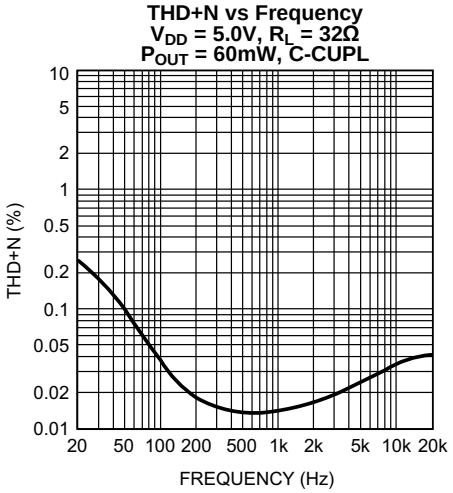


Figure 10.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

THD+N vs Frequency
V_{DD} = 2.5V, R_L = 16Ω
P_{OUT} = 20mW, OCL

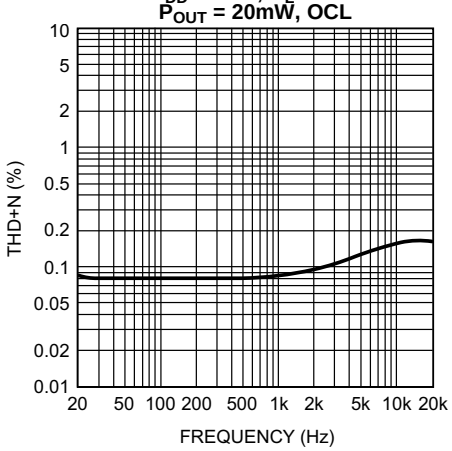


Figure 11.

THD+N vs Frequency
V_{DD} = 3.6V, R_L = 16Ω
P_{OUT} = 50mW, OCL

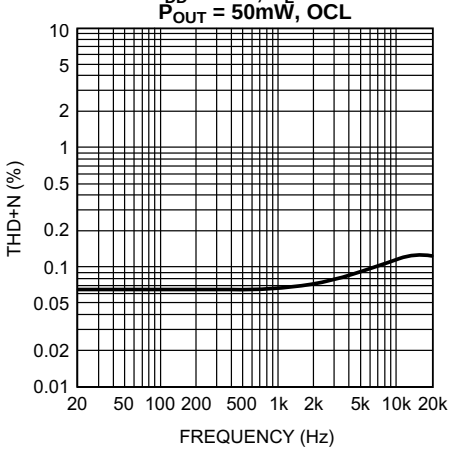


Figure 12.

THD+N vs Frequency
V_{DD} = 5.0V, R_L = 16Ω
P_{OUT} = 50mW, OCL

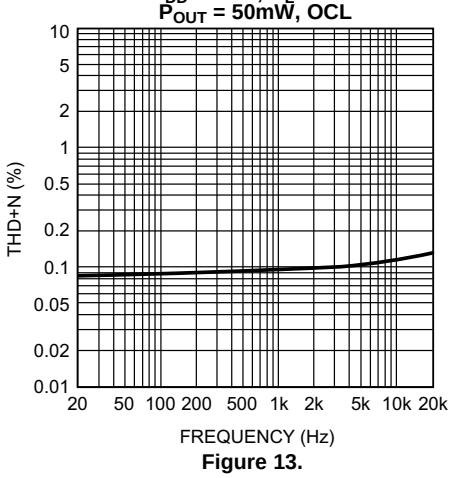


Figure 13.

THD+N vs Frequency
V_{DD} = 2.5V, R_L = 32Ω
P_{OUT} = 15mW, OCL

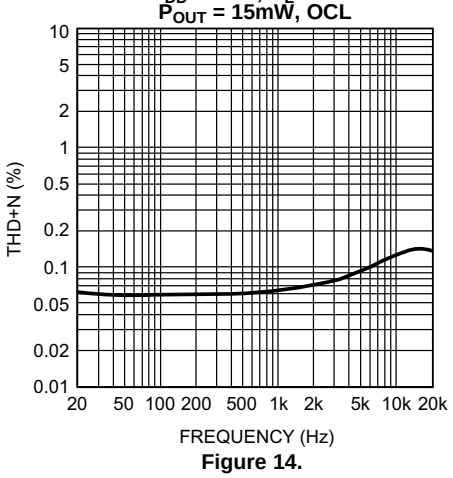


Figure 14.

THD+N vs Frequency
V_{DD} = 3.6V, R_L = 32Ω
P_{OUT} = 35mW, OCL

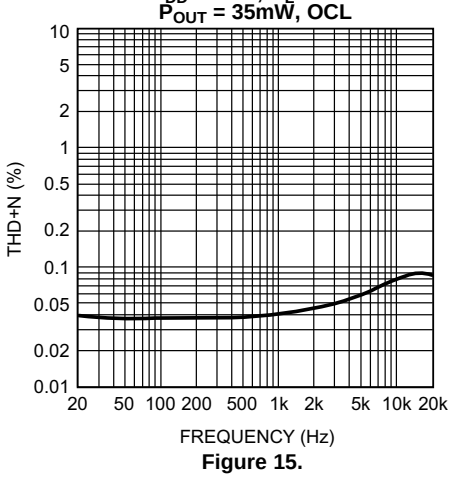


Figure 15.

THD+N vs Frequency
V_{DD} = 5.0V, R_L = 32Ω
P_{OUT} = 60mW, OCL

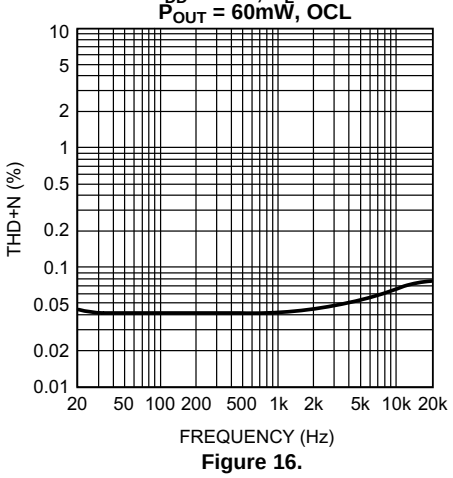


Figure 16.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

THD+N vs Output Power
V_{DD} = 2.5V, R_L = 16Ω
C-CUPL

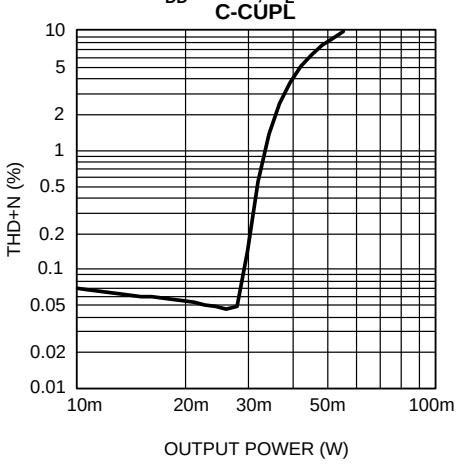


Figure 17.

THD+N vs Output Power
V_{DD} = 3.6V, R_L = 16Ω
C-CUPL

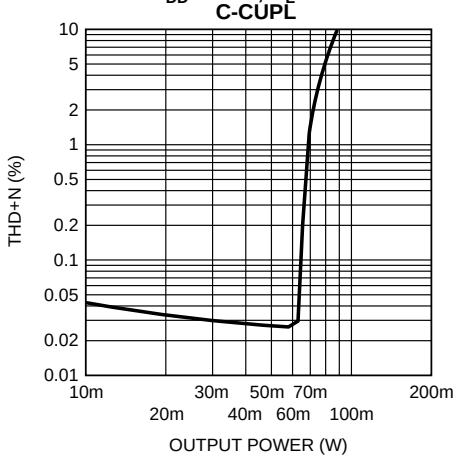


Figure 18.

THD+N vs Output Power
V_{DD} = 5.0V, R_L = 16Ω
C-CUPL

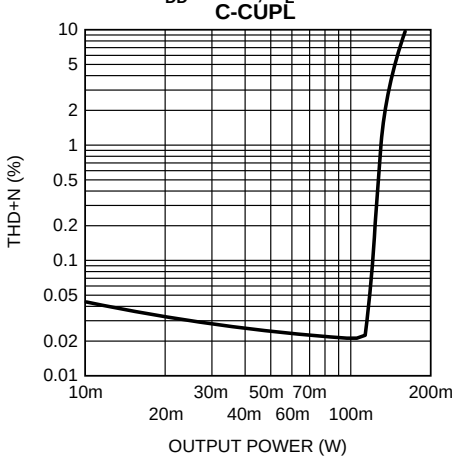


Figure 19.

THD+N vs Output Power
V_{DD} = 2.5V, R_L = 32Ω
C-CUPL

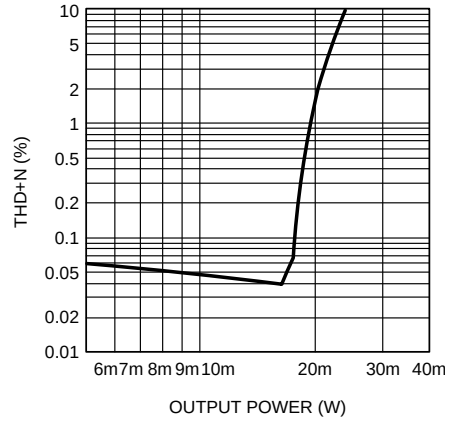


Figure 20.

THD+N vs Output Power
V_{DD} = 3.6V, R_L = 32Ω
C-CUPL

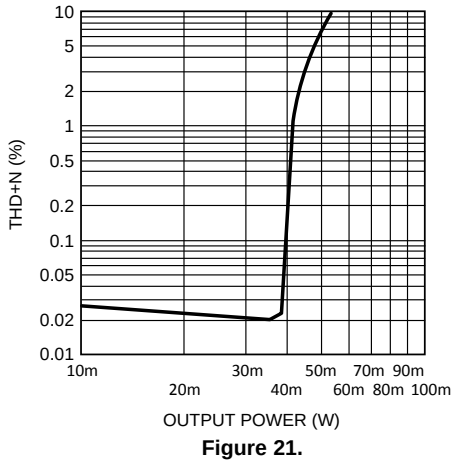


Figure 21.

THD+N vs Output Power
V_{DD} = 5.0V, R_L = 32Ω
C-CUPL

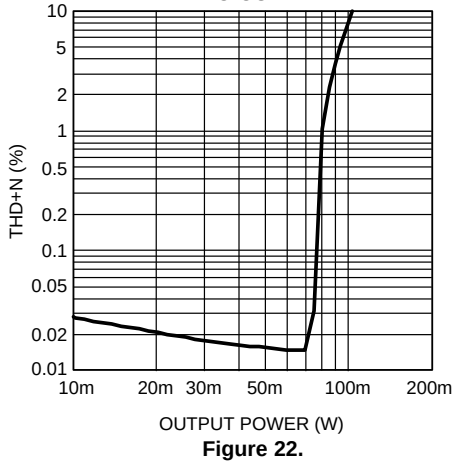


Figure 22.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

THD+N vs Output Power
V_{DD} = 2.5V, R_L = 16Ω
OCL

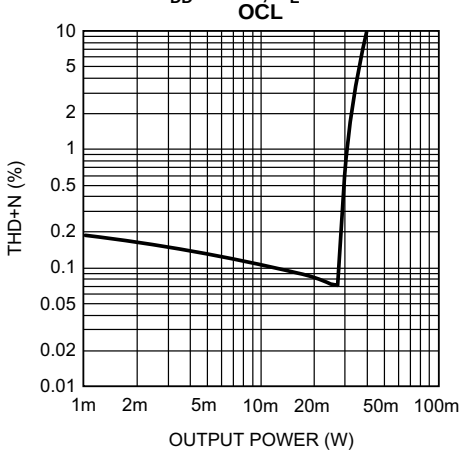


Figure 23.

THD+N vs Output Power
V_{DD} = 3.6V, R_L = 16Ω
OCL

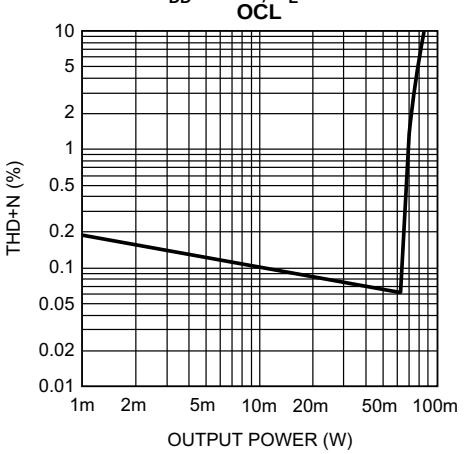


Figure 24.

THD+N vs Output Power
V_{DD} = 5.0V, R_L = 16Ω
OCL

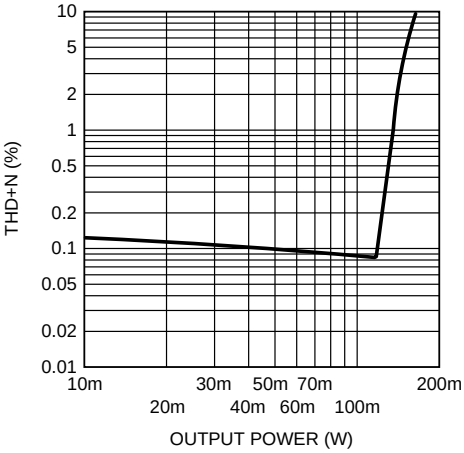


Figure 25.

THD+N vs Output Power
V_{DD} = 2.5V, R_L = 32Ω
OCL

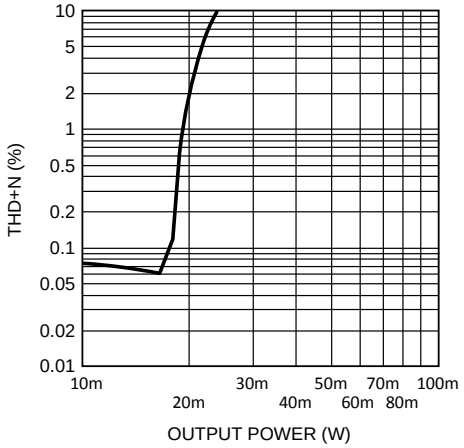


Figure 26.

THD+N vs Output Power
V_{DD} = 3.6V, R_L = 32Ω
OCL

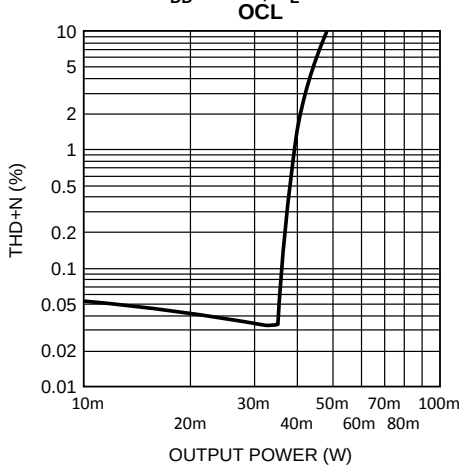


Figure 27.

THD+N vs Output Power
V_{DD} = 5.0V, R_L = 32Ω
OCL

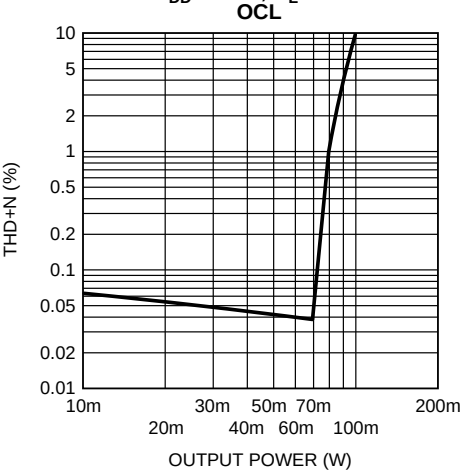


Figure 28.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

PSRR vs Frequency
V_{DD} = 2.5V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, OCL

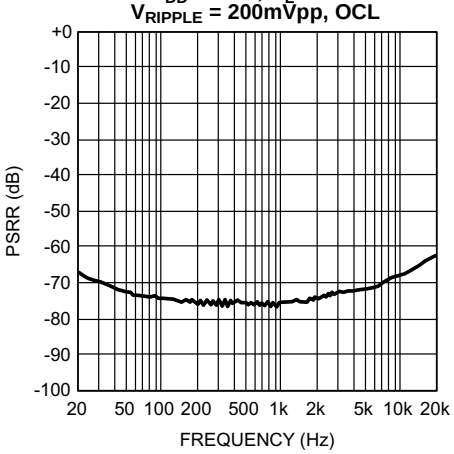


Figure 29.

PSRR vs Frequency
V_{DD} = 3.6V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, OCL

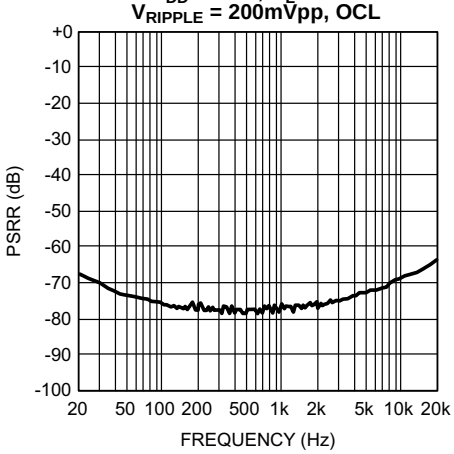


Figure 30.

PSRR vs Frequency
V_{DD} = 5.0V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, OCL

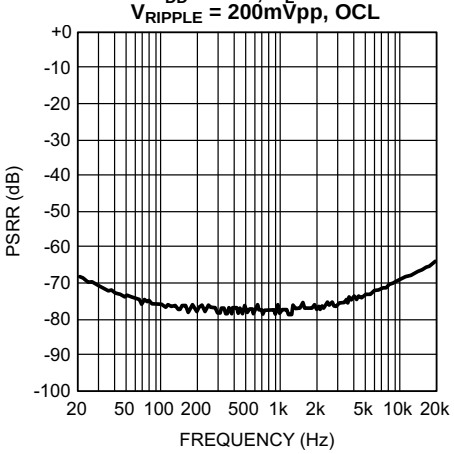


Figure 31.

PSRR vs Frequency
V_{DD} = 2.5V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, OCL

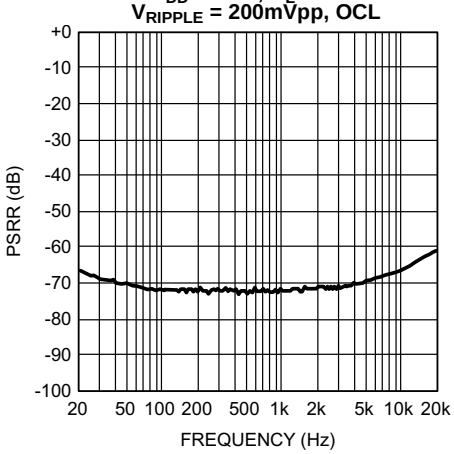


Figure 32.

PSRR vs Frequency
V_{DD} = 3.6V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, OCL

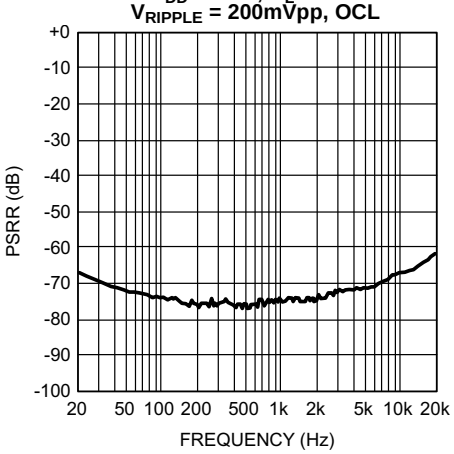


Figure 33.

PSRR vs Frequency
V_{DD} = 5.0V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, OCL

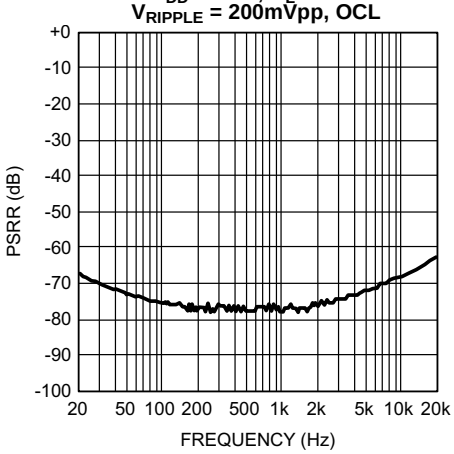


Figure 34.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

PSRR vs Frequency
V_{DD} = 2.5V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, C-CUPL

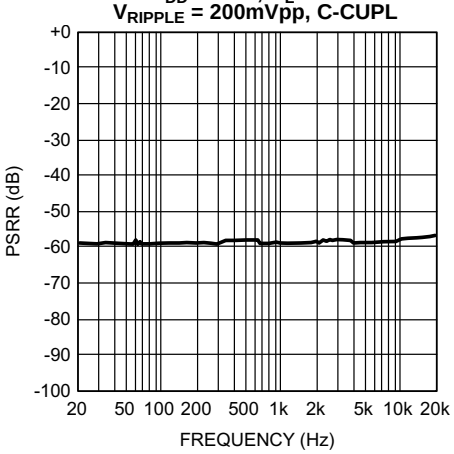


Figure 35.

PSRR vs Frequency
V_{DD} = 3.6V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, C-CUPL

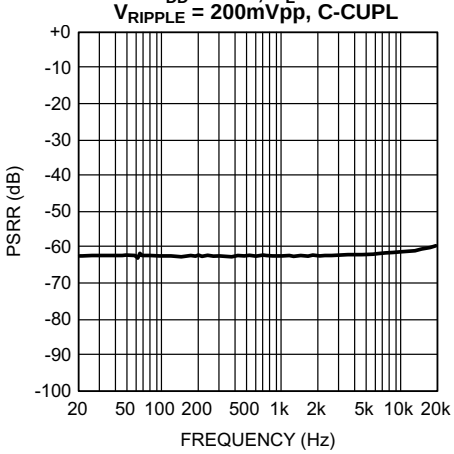


Figure 36.

PSRR vs Frequency
V_{DD} = 5.0V, R_L = 16Ω
V_{RIPPLE} = 200mVpp, C-CUPL

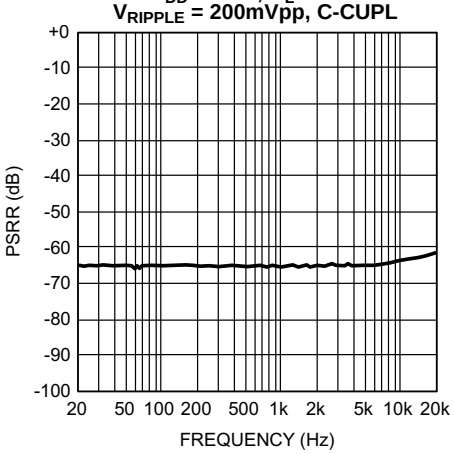


Figure 37.

PSRR vs Frequency
V_{DD} = 2.5V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, C-CUPL

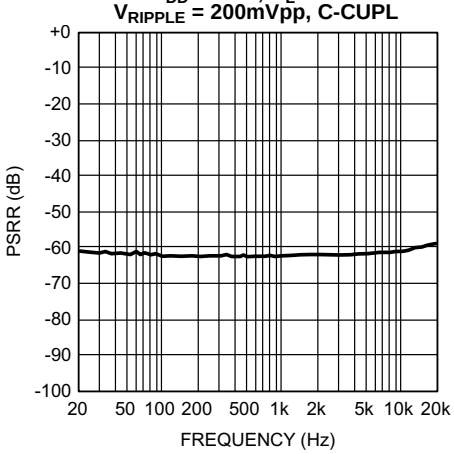


Figure 38.

PSRR vs Frequency
V_{DD} = 3.6V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, C-CUPL

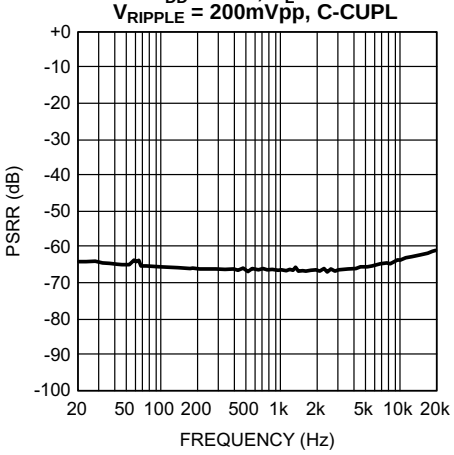


Figure 39.

PSRR vs Frequency
V_{DD} = 5.0V, R_L = 32Ω
V_{RIPPLE} = 200mVpp, C-CUPL

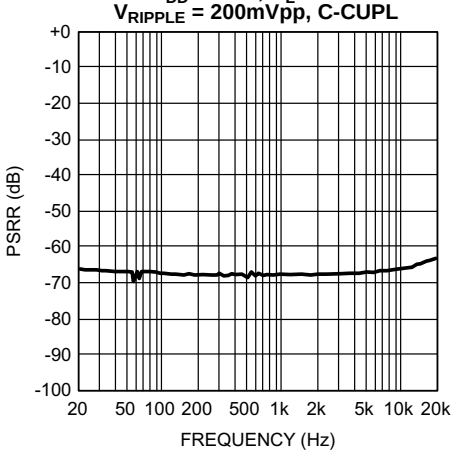


Figure 40.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Crosstalk vs Frequency
V_{DD} = 2.5V, R_L = 16Ω
P_{OUT} = 20mW. OCL

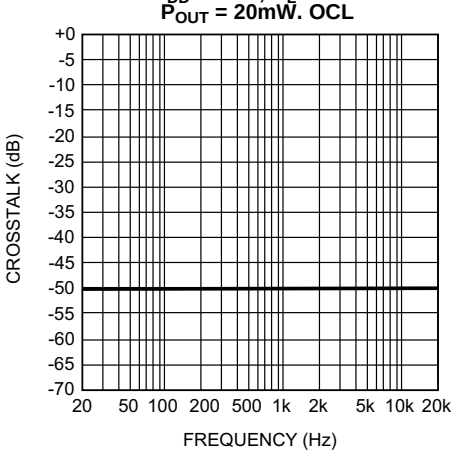


Figure 41.

Crosstalk vs Frequency
V_{DD} = 3.6V, R_L = 16Ω
P_{OUT} = 40mW, OCL

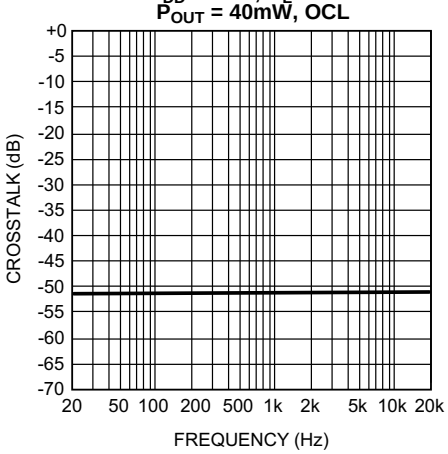


Figure 42.

Crosstalk vs Frequency
V_{DD} = 5.0V, R_L = 16Ω
P_{OUT} = 40mW, OCL

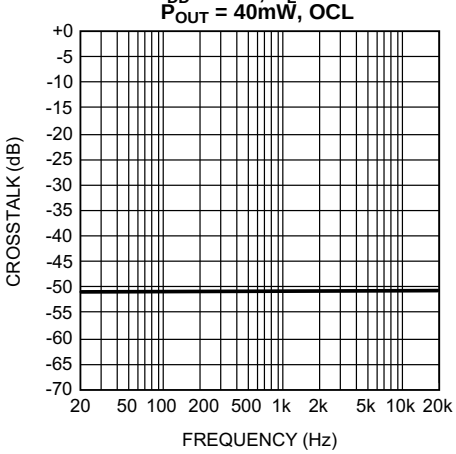


Figure 43.

Crosstalk vs Frequency
V_{DD} = 2.5V, R_L = 32Ω
P_{OUT} = 20mW, OCL

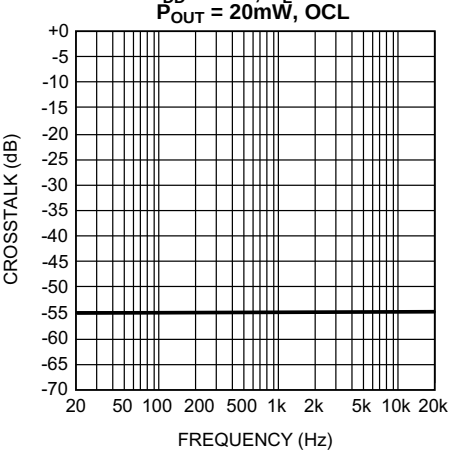


Figure 44.

Crosstalk vs Frequency
V_{DD} = 3.6V, R_L = 32Ω
P_{OUT} = 40mW, OCL

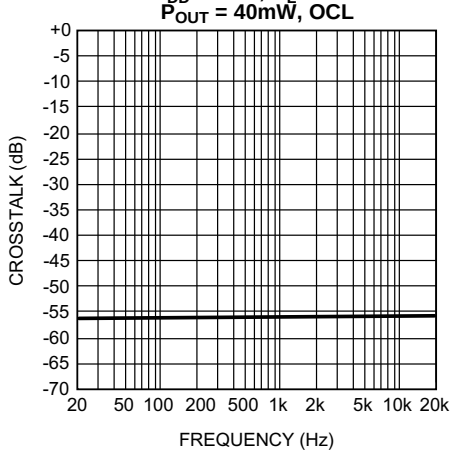


Figure 45.

Crosstalk vs Frequency
V_{DD} = 5.0V, R_L = 32Ω
P_{OUT} = 50mW, OCL

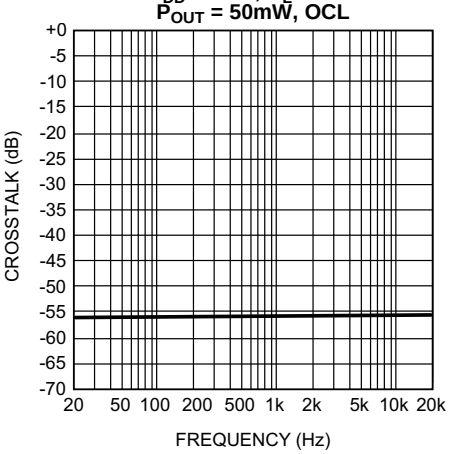


Figure 46.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Crosstalk vs Frequency
V_{DD} = 2.5V, R_L = 16Ω
P_{OUT} = 20mW, C-CUPL

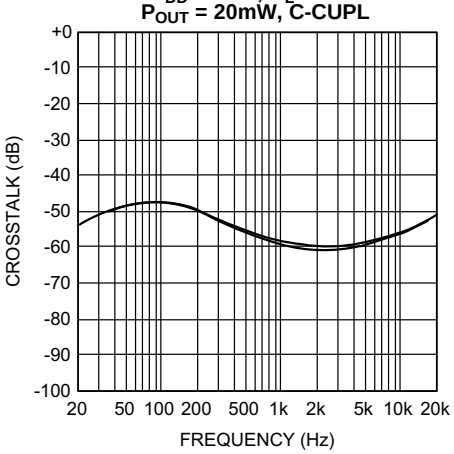


Figure 47.

Crosstalk vs Frequency
V_{DD} = 3.6V, R_L = 16Ω
P_{OUT} = 50mW, C-CUPL

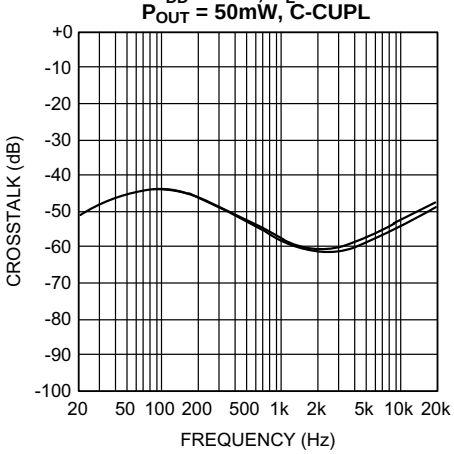


Figure 48.

Crosstalk vs Frequency
V_{DD} = 5.0V, R_L = 16Ω
P_{OUT} = 50mW, C-CUPL

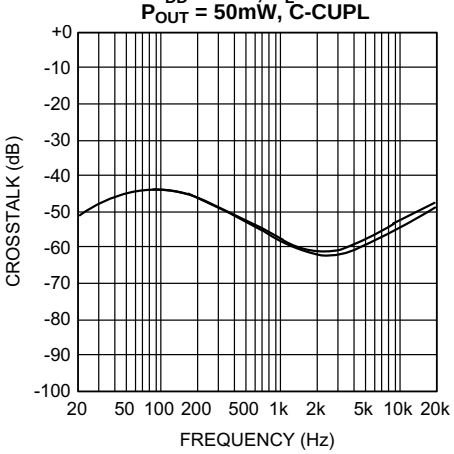


Figure 49.

Crosstalk vs Frequency
V_{DD} = 2.5V, R_L = 32Ω
P_{OUT} = 20mW, C-CUPL

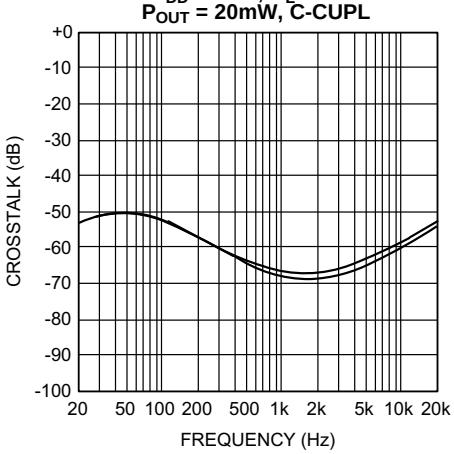


Figure 50.

Crosstalk vs Frequency
V_{DD} = 3.6V, R_L = 32Ω
P_{OUT} = 50mW, C-CUPL

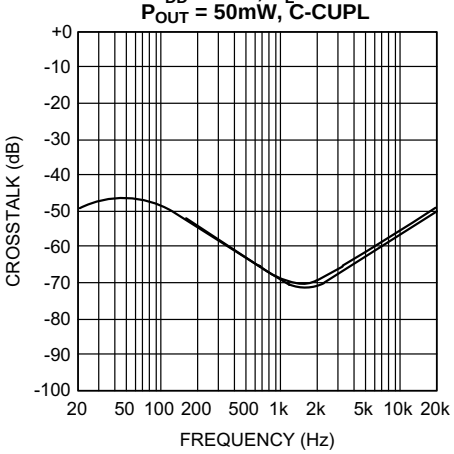


Figure 51.

Crosstalk vs Frequency
V_{DD} = 5.0V, R_L = 32Ω
P_{OUT} = 50mW, C-CUPL

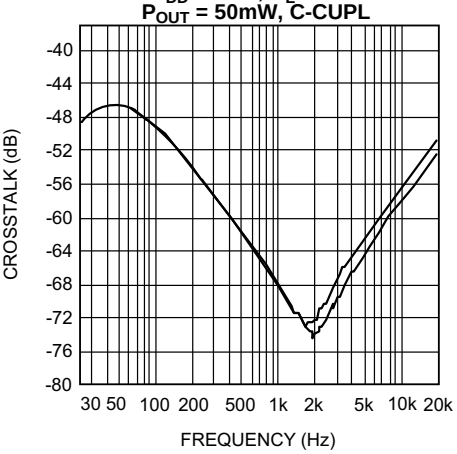


Figure 52.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 2.5V, C-CUPL

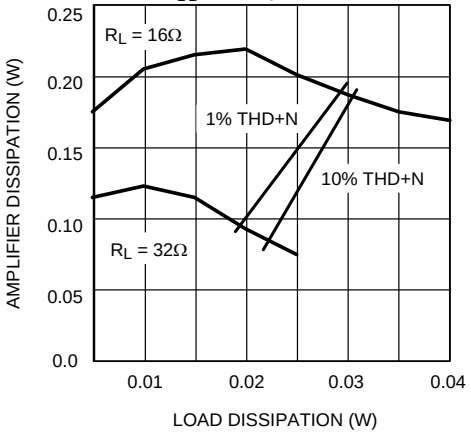


Figure 53.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 3.6V, C-CUPL

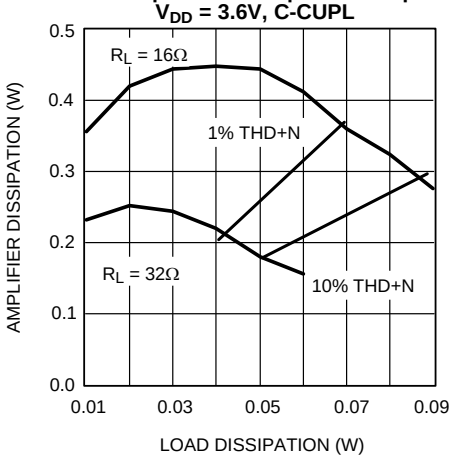


Figure 54.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 5.0V, C-CUPL

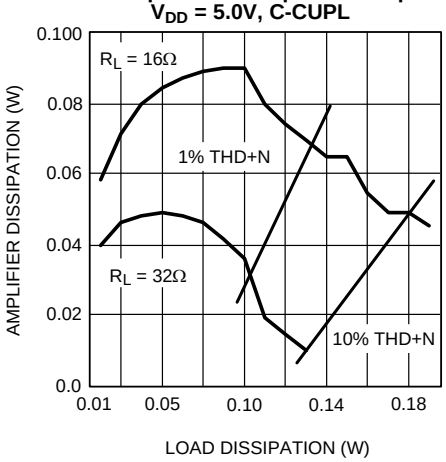


Figure 55.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 2.5V, OCL

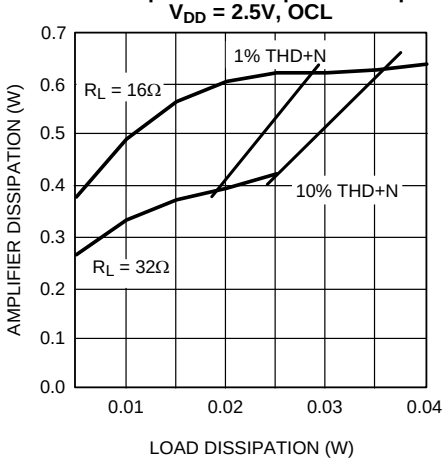


Figure 56.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 3.6V, OCL

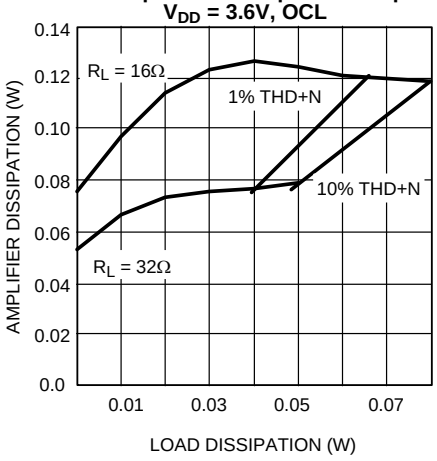


Figure 57.

Load Dissipation vs Amplifier Dissipation
V_{DD} = 5.0V, OCL

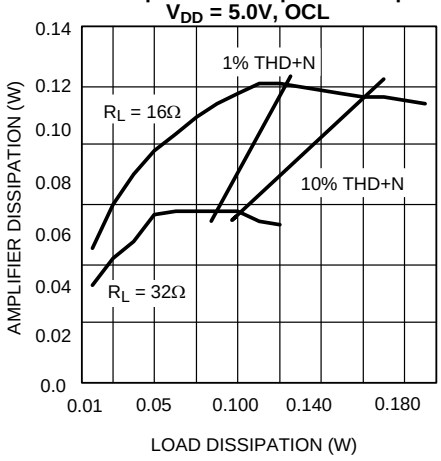


Figure 58.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Output Power vs Load Resistance
V_{DD} = 2.5V, C-CUPL

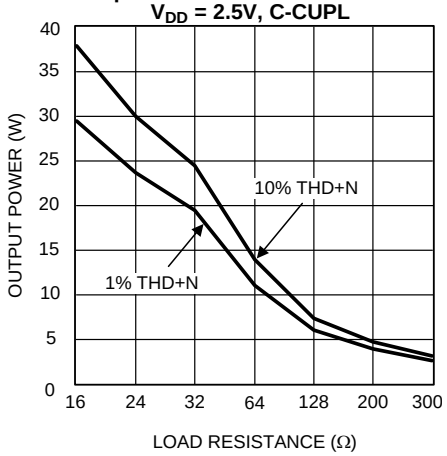


Figure 59.

Output Power vs Load Resistance
V_{DD} = 3.6V, C-CUPL

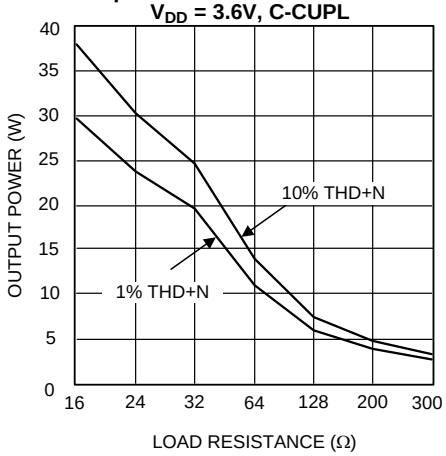


Figure 60.

Output Power vs Load Resistance
V_{DD} = 5.0V, C-CUPL

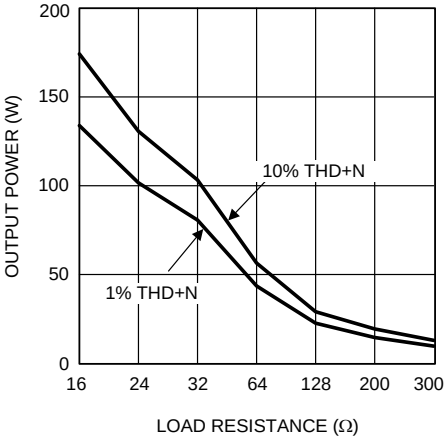


Figure 61.

Output Power vs Load Resistance
V_{DD} = 2.5V, OCL

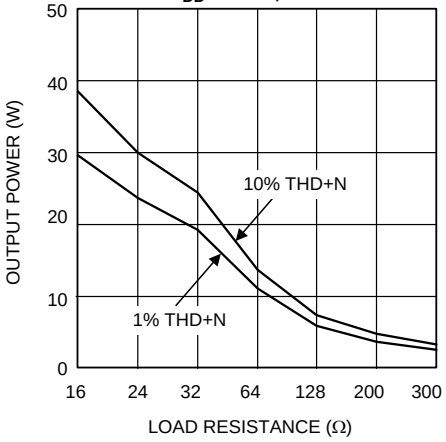


Figure 62.

Output Power vs Load Resistance
V_{DD} = 3.6V, OCL

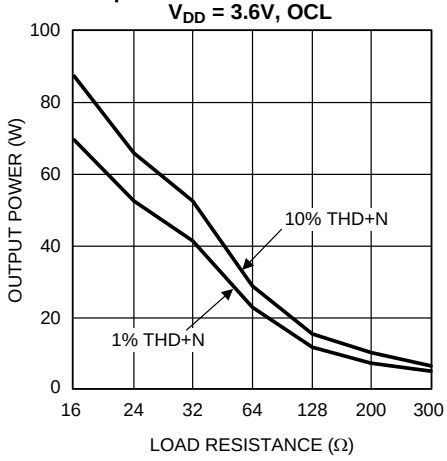


Figure 63.

Output Power vs Load Resistance
V_{DD} = 5.0V, OCL

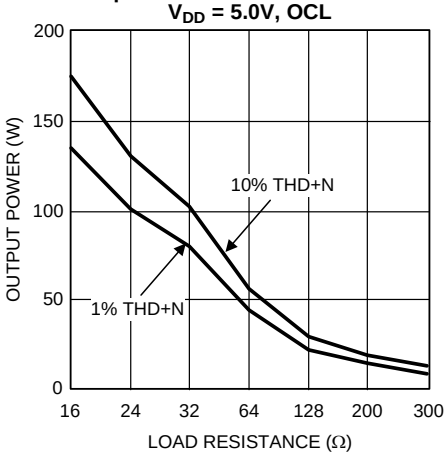


Figure 64.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Output Power vs Supply Voltage
R_L = 16Ω, C-CUPL

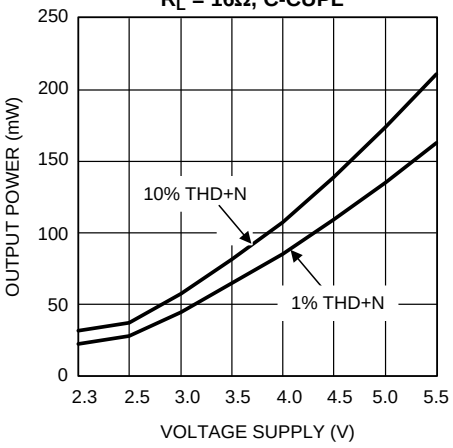


Figure 65.

Output Power vs Supply Voltage
R_L = 32Ω, C-CUPL

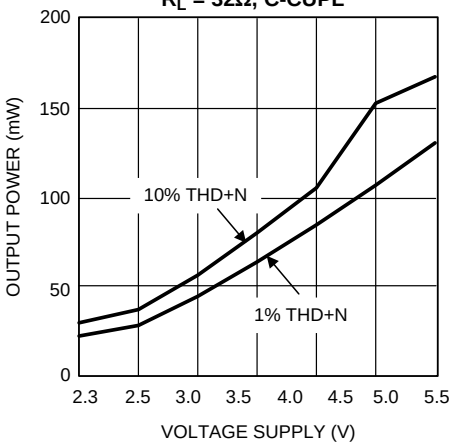


Figure 66.

Output Power vs Supply Voltage
R_L = 16Ω, OCL

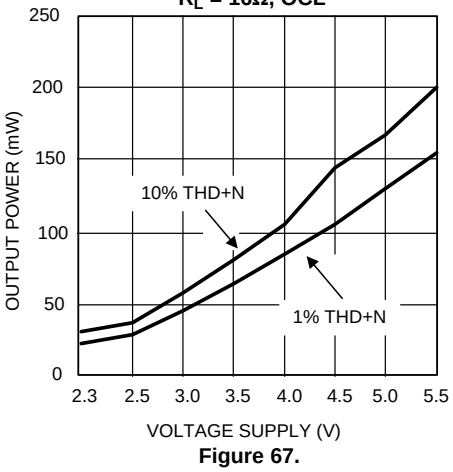


Figure 67.

Output Power vs Supply Voltage
R_L = 32Ω, OCL

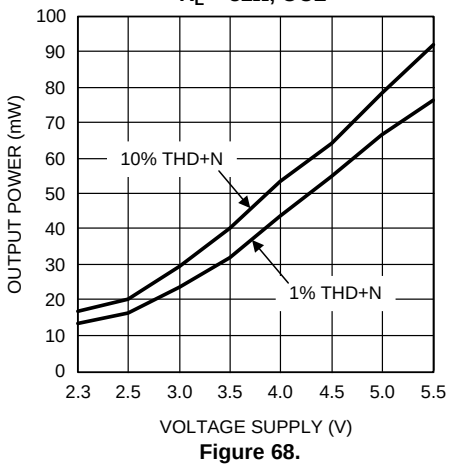


Figure 68.

Supply Current vs Supply Voltage
R_L = 16Ω, C-CUPL

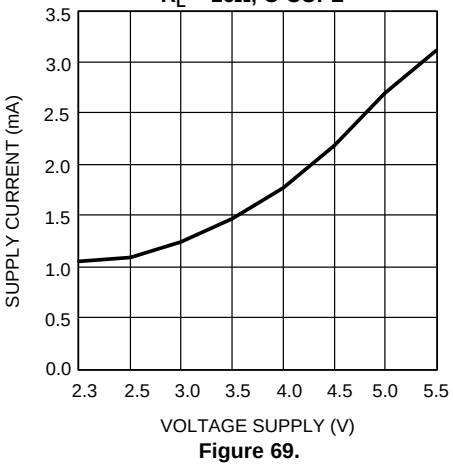


Figure 69.

Supply Current vs Supply Voltage
R_L = 32Ω, C-CUPL

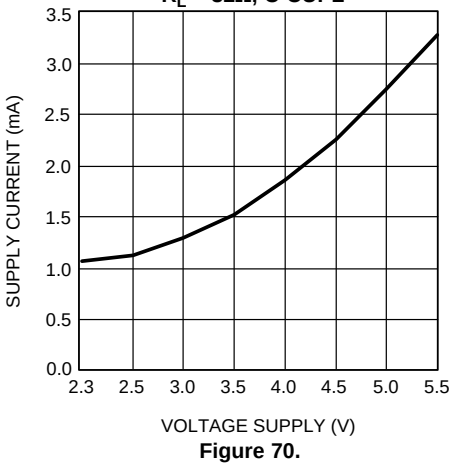


Figure 70.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

Supply Current vs Supply Voltage
R_L = 16Ω, OCL

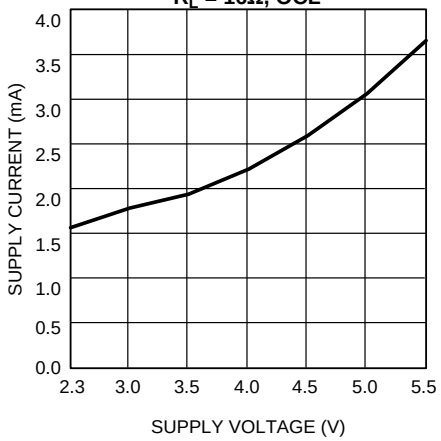


Figure 71.

Supply Current vs Supply Voltage
R_L = 32Ω, OCL

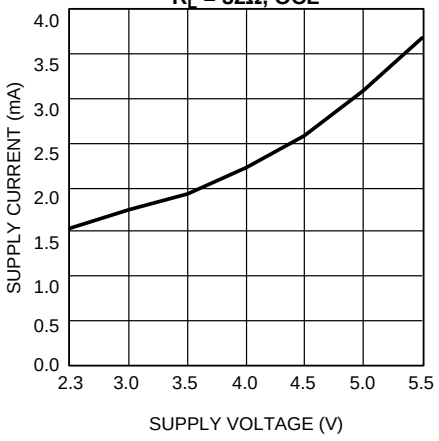


Figure 72.

Gain vs Volume Steps
V_{CC} = 2.5V, R_L = 16Ω, OCL

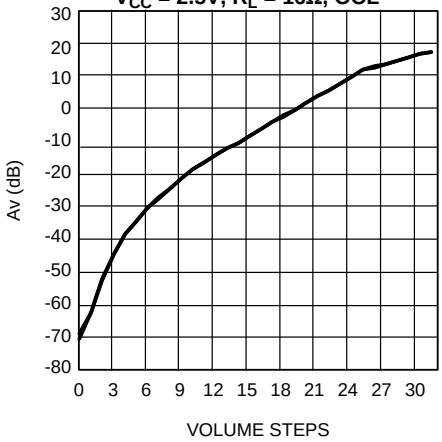


Figure 73.

Gain vs Volume Steps
V_{CC} = 3.6V, R_L = 16Ω, OCL

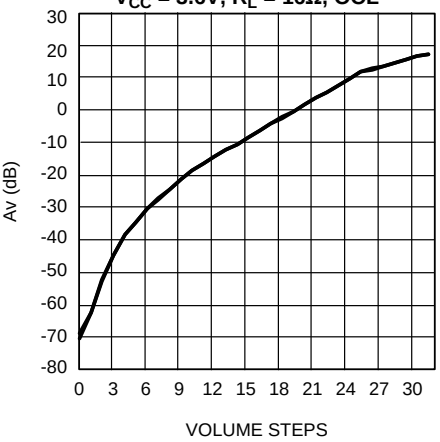


Figure 74.

Gain vs Volume Steps
V_{CC} = 5V, R_L = 16Ω, OCL

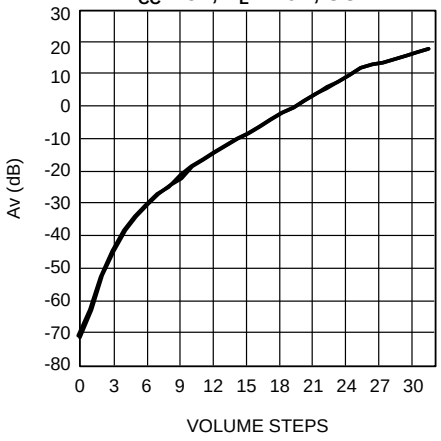


Figure 75.

Gain vs Volume Steps
V_{CC} = 2.5V, R_L = 16Ω, C-CUPL

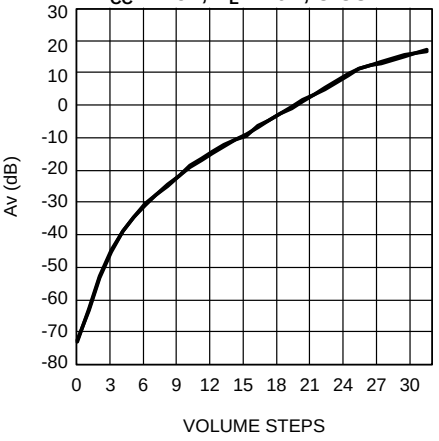


Figure 76.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

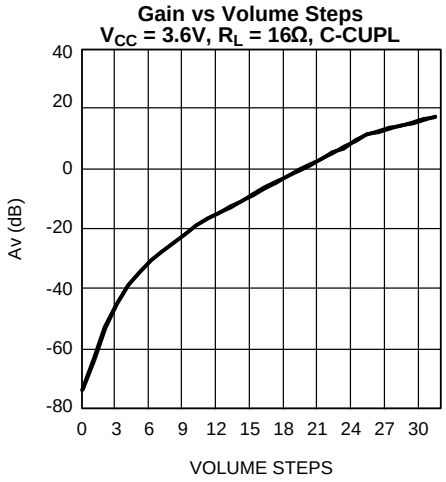


Figure 77.

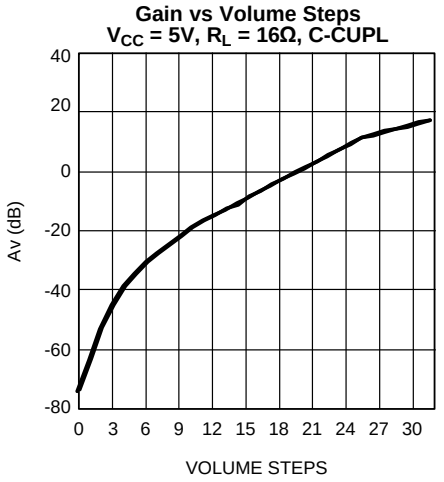


Figure 78.

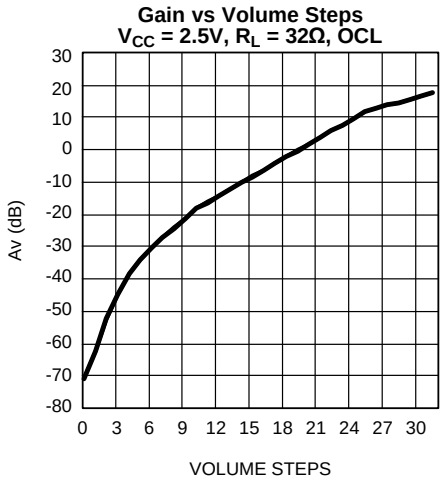


Figure 79.

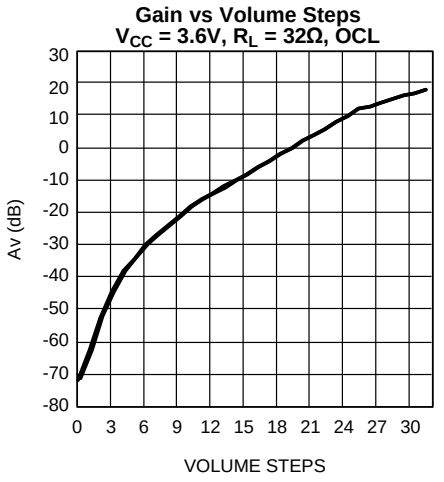


Figure 80.

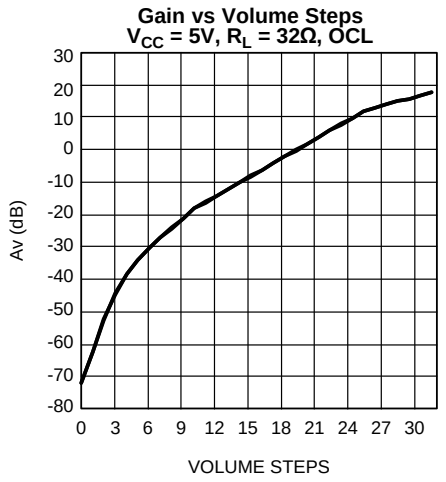


Figure 81.

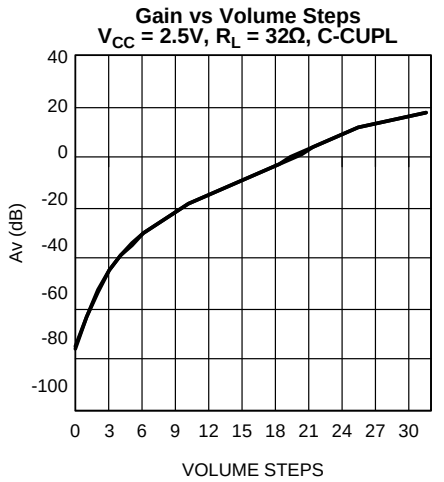


Figure 82.

Typical Performance Characteristics (continued)

T_A = 25°C, A_V = 0dB, f_{IN} = 1kHz unless otherwise stated.

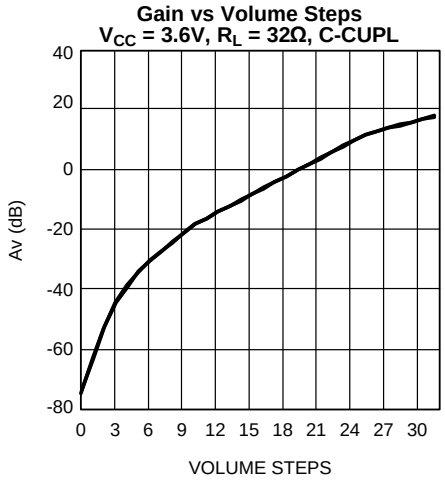


Figure 83.

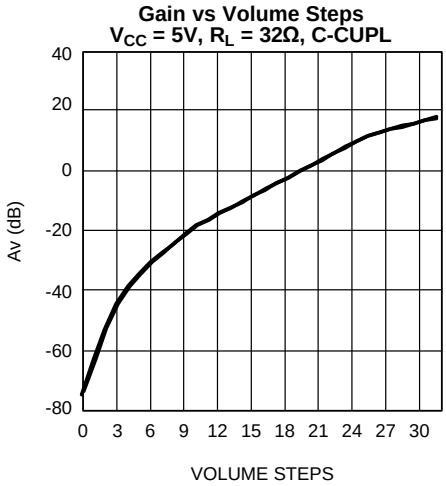


Figure 84.

APPLICATION INFORMATION

AMPLIFIER CONFIGURATION EXPLANATION

As shown in Figure 1, the LM4985 has three internal power amplifiers. Two of the amplifiers which amplify signals applied to their inputs, have internally configurable gain. The remaining third amplifier provides both half-supply output bias and AC ground return.

Loads, such as a headphone speaker, are connected between OUT1 and CNTGND or OUT2 and CNTGND. This configuration does not require an output coupling capacitor. The classical single-ended amplifier configuration, where one side of the load is connected to ground, requires large, expensive output coupling capacitors.

A configuration such as the one used in the LM4985 has a major advantage over single supply, single-ended amplifiers. Since the outputs OUT1, OUT2, and CNTGND are all biased at 1/2 V_{DD}, no net DC voltage exists across each load. This eliminates the need for output coupling capacitors which are required in a single-supply, single-ended amplifier configuration. Without output coupling capacitors in a typical single-supply, single-ended amplifier, the bias voltage is placed across the load resulting in both increased internal IC power dissipation and possible loudspeaker damage.

The LM4985 eliminates these output coupling capacitors when operating in Output Capacitor-less (OCL) mode. Unless shorted to ground, VoC is internally configured to apply a 1/2 V_{DD} bias voltage to a stereo headphone jack's sleeve. This voltage matches the bias voltage present on VoA and VoB outputs that drive the headphones. The headphones operate in a manner similar to a bridge-tied load (BTL). Because the same DC voltage is applied to both headphone speaker terminals this results in no net DC current flow through the speaker. AC current flows through a headphone speaker as an audio signal's output amplitude increases on the speaker's terminal.

The headphone jack's sleeve is not connected to circuit ground when used in OCL mode. Using the headphone output jack as a line-level output will place the LM4985's 1/2 V_{DD} bias voltage on a plug's sleeve connection. This presents no difficulty when the external equipment uses capacitively coupled inputs. For the very small minority of equipment that is DC coupled, the LM4985 monitors the current supplied by the amplifier that drives the headphone jack's sleeve. If this current exceeds 500mA_{PEAK}, the amplifier is shutdown, protecting the LM4985 and the external equipment.

POWER DISSIPATION

Power dissipation is a major concern when using any power amplifier. When operating in capacitor-coupled mode (C-CUPL), Equation 1 states the maximum power dissipation point for a single-ended amplifier operating at a given supply voltage and driving a specified output load.

$$P_{DMAX} = 2(V_{DD})^2 / (2\pi^2 R_L) \quad (1)$$

When operating in the OCL mode, the LM4985's three operational amplifiers produce a maximum power dissipation given in Equation 2:

$$P_{DMAX} = [2(V_{DD})^2 / (2\pi^2 R_L)] + [V_{DD}^2 / (4\pi R_L)] \quad (2)$$

The maximum power dissipation point obtained from Equation 1 or Equation 2 must not be greater than the power dissipation that results from Equation 3:

$$P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA} \quad (3)$$

For package YFQ0012, θ_{JA} = 190°C/W. T_{JMAX} = 150°C for the LM4985. Depending on the ambient temperature, T_A, of the system surroundings, Equation 3 can be used to find the maximum internal power dissipation supported by the IC packaging. If the result of Equation 2 is greater than that of Equation 3, then either the supply voltage must be decreased, the load impedance increased or T_A reduced.

For a typical application using a 3.6V power supply, with a 32Ω load, the maximum ambient temperature possible without violating the maximum junction temperature is approximately 144°C provided that device operation is around the maximum power dissipation point. Thus, for typical applications, power dissipation is not an issue. Power dissipation is a function of output power and thus, if typical operation is not around the maximum power dissipation point, the ambient temperature may be increased accordingly. Refer to the Typical Performance Characteristics curves for power dissipation information for lower output powers.

POWER SUPPLY BYPASSING

As with any amplifier, proper supply bypassing is important for low noise performance and high power supply rejection. The capacitor location on the power supply pins should be as close to the device as possible.

Typical applications employ a regulator with 10µF tantalum or electrolytic capacitor and a ceramic bypass capacitor which aid in supply stability. This does not eliminate the need for bypassing the supply nodes of the LM4985. A bypass capacitor value in the range of 0.1µF to 1µF is recommended for C_S.

MICRO POWER SHUTDOWN

The LM4985's micropower shutdown is activated or deactivated through its I^2C digital interface . Please refer to Table 1 for the I^2C Address, Register Select, and Mode Control registers. Each amplifier within the LM4985 can be shutdown individually.

Please observe the following protocol when placing an individual amplifier channel in shutdown while the other channel remains active. The protocol requires activating both channels' shutdown simultaneously, then deactivating the shutdown of the channel whose output is desired (or leaving the desire channel in shutdown mode). Also, when operating in the C-CUPL mode, a short delay time is required between activating one channel after placing both channels in shutdown. If the user finds that both channels activate when only one was chosen, increase the delay.

SELECTION OF INPUT CAPACITOR SIZE

Amplifying the lowest audio frequencies requires a high value input coupling capacitor, C_i. A high value capacitor can be expensive and may compromise space efficiency in portable designs. In many cases, however, the headphones used in portable systems have little ability to reproduce signals below 60Hz. Applications using headphones with this limited frequency response reap little improvement by using a high value input capacitor.

In addition to system cost and size, turn on time is affected by the size of the input coupling capacitor C_i. A larger input coupling capacitor requires more charge to reach its quiescent DC voltage. This charge comes from the output via the feedback Thus, by minimizing the capacitor size based on necessary low frequency response, turn-on time can be minimized. A small value of C_i (in the range of 0.22µF to 0.68µF), is recommended.

MAXIMIZING OCL MODE CHANNEL-to-CHANNEL SEPARATION

The OCL mode AC ground return (CNT_GND pin) is shared by both amplifiers. As such, any resistance between the CNT_GND pin and the load will create a voltage divider with respect to the load resistance. In a typical circuit, the amount of CNT_GND resistance can be very small, but still significant. It is significant because of the relatively low load impedances for which the LM4985 was designed to drive: 16Ω to 32Ω. The ratio of this voltage divider will determine the magnitude of any residual signal present at the CNT_GND pin. It is this residual signal that leads to channel-to-channel separation (crosstalk) degradation.

For example, for a 60dB channel-to-channel separation while driving a 16Ω load, the resistance between the LM4985's CNT_GND pin and the load must be less than 16mΩ. This is achieved by ensuring that the trace that connects the CNT_GND pin to the headphone jack sleeve should be as short and massive as possible, given the physical constraints of any specific printed circuit board layout and design.

DEMONSTRATION BOARD AND PCB LAYOUT

Information concerning PCB layout considerations and demonstration board use and performance is found in Application Note AN-1452 (Literature Number SNAA029).

I²C Control Register

Table 1 shows the actions that are implemented by manipulating the bits within the two internal I²C control registers.

Table 1. LM4985 I²C Control Register Addressing and Data Format Chart

	LM4985 I2C Contorl Register Addressing and Data Chart								
I2C Address		A6	A5	A4	A3	A2	A1	A0	Function
		1	1	0	0	1	1	A0	
Register Select	D7	D6	D5	D4	D3	D2	RS1	RS0	
	0	0	0	0	0	0	0	0	Read and write the mode control register
	0	0	0	0	0	0	0	1	Read and write the volume control register
Mode Control Register	D7	D6	D5	D4	D3	D2	D1	D0	
		WT1	WT0	PHG	SDCH1	SDCH2	CHSEL1	CHSEL2	
	0	X	X	X	X	X	X	X	D7 must always be set to 0
	–	0	0	X	X	X	X	X	Wake-up time: 80ms (OCL), 250ms (C-CUPL)
	–	0	1	X	X	X	X	X	Wake-up time: 110ms (OCL), 450ms (C-CUPL)
	–	1	0	X	X	X	X	X	Wake-up time: 170ms (OCL), 850ms (C-CUPL)
	–	1	1	X	X	X	X	X	Wake-up time: 290ms (OCL), 1650ms (C-CUPL)
	–	X	X	1	X	X	X	X	Output capacitor-less mode **active**
	–	X	X	0	X	X	X	X	Output capacitor-less mode **inactive**
	–	X	X	X	0	0	X	X	Amplifier's SHUTDOWN mode **active**
	–	X	X	X	0	1	X	X	Illegal mode
	–	X	X	X	1	0	X	X	Illegal mode
	–	X	X	X	1	1	X	X	Amplifier's SHUTDOWN mode **inactive**
	–	X	X	X	X	X	0	02	Amplifier's Chan. 1 is **Input 1**, Chan 2. is **Input 2**
	–	X	X	X	X	X	0	1	Amplifier's Chan. 1 is **Input 1**, Chan 2. is **Input 1**
	–	X	X	X	X	X	1	0	Amplifier's Chan. 1 is **Input 2**, Chan 2. is **Input 2**
	–	X	X	X	X	X	1	1	Amplifier's Chan. 1 is **Input 2**, Chan 2. is **Input 1**

Volume Control Settings Binary Values

The minimum volume setting is set to –76dB when 00000 is loaded into the volume control register. Incrementing the volume control register in binary fashion increases the volume control setting, reaching full scale at 11111. Table 2 shows the value of the gain for each of the 32 binary volume control settings.

Table 2. Binary Values for the Different Volume Control Gain Settings

Gain	B4	B3	B2	B1	B0
18	1	1	1	1	1
17	1	1	1	1	0
16	1	1	1	0	1
15	1	1	1	0	0
14	1	1	0	1	1
13	1	1	0	1	0
12	1	1	0	0	1
10	1	1	0	0	0
8	1	0	1	1	1
6	1	0	1	1	0
4	1	0	1	0	1
2	1	0	1	0	0
0	1	0	0	1	1
–2	1	0	0	1	0
–4	1	0	0	0	1
–6	1	0	0	0	0
–8	0	1	1	1	1
–10	0	1	1	1	0
–12	0	1	1	0	1
–14	0	1	1	0	0
–16	0	1	0	1	1
–18	0	1	0	1	0
–21	0	1	0	0	1
–24	0	1	0	0	0
–27	0	0	1	1	1
–30	0	0	1	1	0
–34	0	0	1	0	1
–38	0	0	1	0	0
–44	0	0	0	1	1
–52	0	0	0	1	0
–62	0	0	0	0	1
–76	0	0	0	0	0

Revision History

Rev	Date	Description
1.0	05/17/06	Initial WEB release.

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format	27

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM4985TM/NOPB	ACTIVE	DSBGA	YFQ	12	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G H2	Samples
LM4985TMX/NOPB	ACTIVE	DSBGA	YFQ	12	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G H2	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

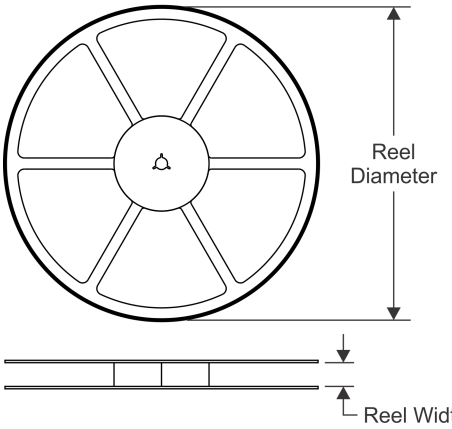
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

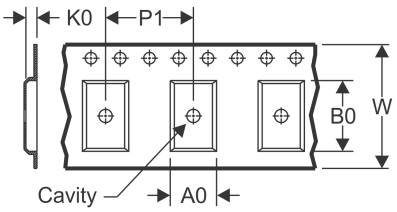
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

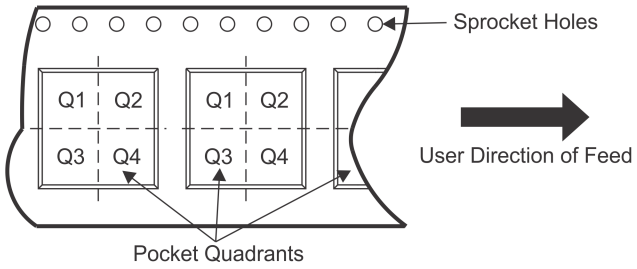


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

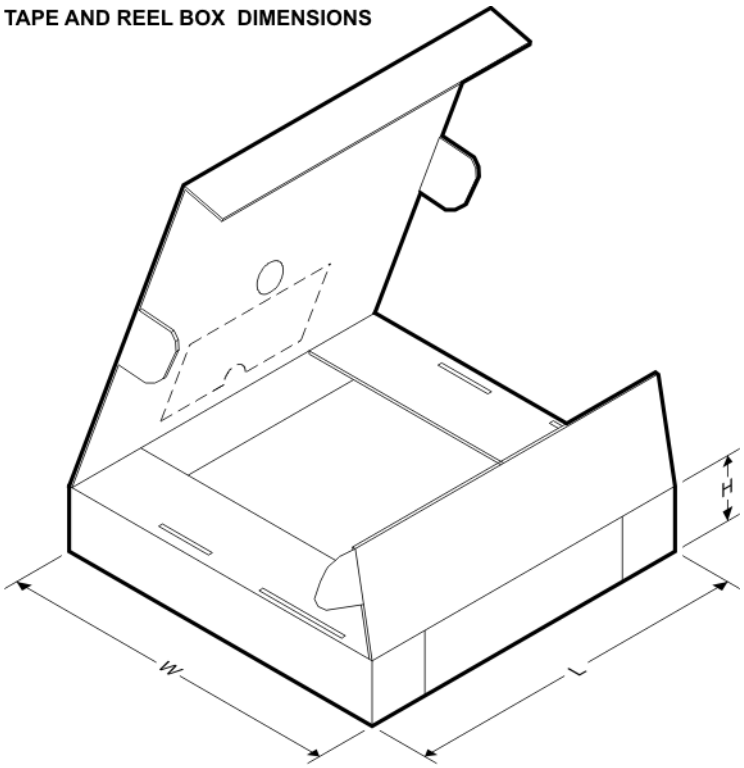
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4985TM/NOPB	DSBGA	YFQ	12	250	178.0	8.4	1.35	1.75	0.76	4.0	8.0	Q1
LM4985TMX/NOPB	DSBGA	YFQ	12	3000	178.0	8.4	1.35	1.75	0.76	4.0	8.0	Q1

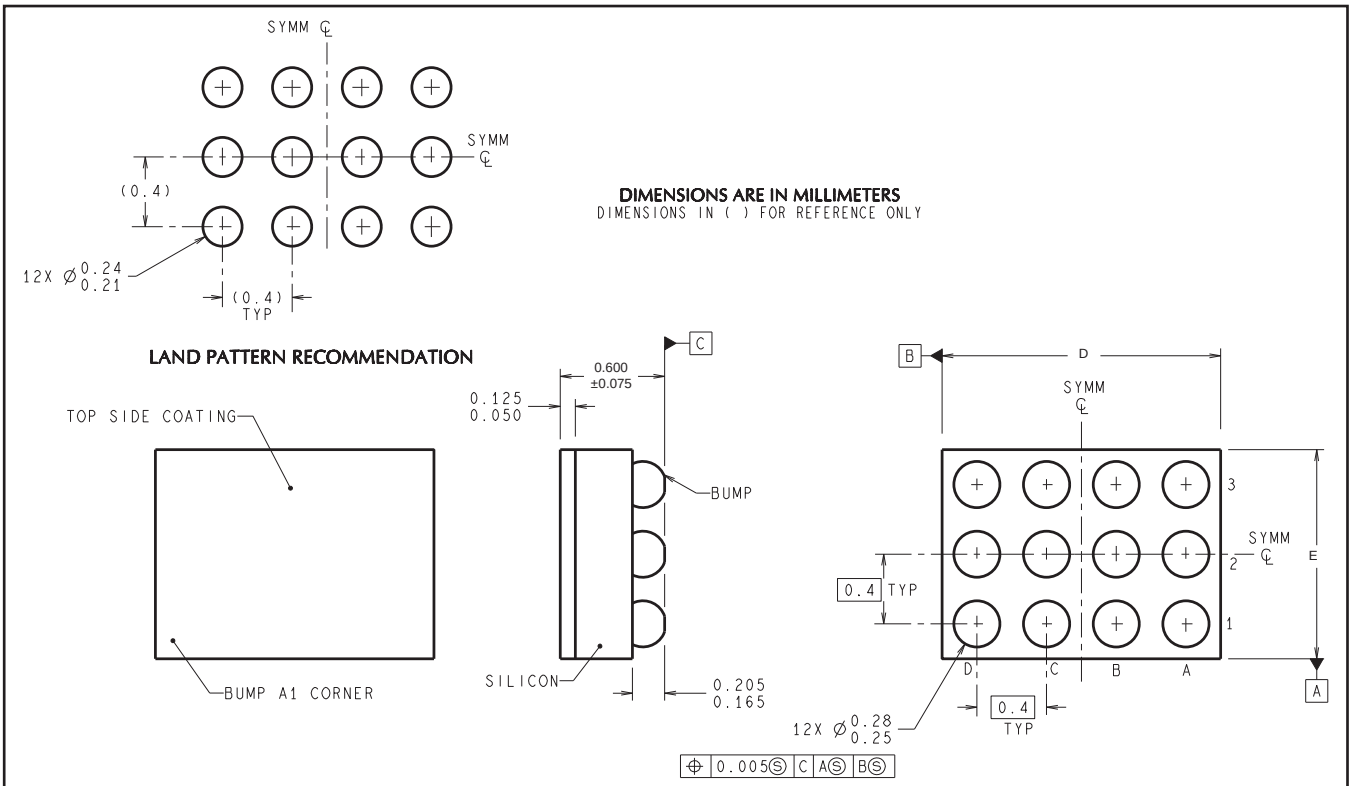
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4985TM/NOPB	DSBGA	YFQ	12	250	210.0	185.0	35.0
LM4985TMX/NOPB	DSBGA	YFQ	12	3000	210.0	185.0	35.0

YFQ0012



D: Max = 1.64 mm, Min = 1.58 mm

E: Max = 1.24 mm, Min = 1.18 mm

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NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

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